



FORM PTO-1449 (REV. 7-80)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. NIT-288		SERIAL NO.		
LIST OF DOCUMENTS CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT N. KOFUJI et al				
				FILING DATE August 3, 2001		GROUP		
U.S. PATENT DOCUMENTS								
* EXAMINER INITIAL		DOCUMENT	DATE	NAME	CLASS	SUBCLASS	FILING DATE (If Appropriate)	
(previously considered)	AA	<del>6,232,237</del>	<del>5/15/01</del>	<del>Tamaoka et al</del>				
	AB							
	AC							
	AD							
	AE							
	AF							
	AG							
	AH							
	AI							
	AJ							
	AK							
FOREIGN PATENT DOCUMENTS								
		DOCUMENT	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
(previously considered)	AL	<del>11-126814</del>	<del>07/02/99</del>	<del>Japan</del>			<input type="checkbox"/>	<input type="checkbox"/>
	AM						<input type="checkbox"/>	<input type="checkbox"/>
	AN						<input type="checkbox"/>	<input type="checkbox"/>
	AO						<input type="checkbox"/>	<input type="checkbox"/>
	AP						<input type="checkbox"/>	<input type="checkbox"/>
OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)								
(previously considered)	AR	TECHNICAL REPORT OF IEICE: "Technique for Forming Cu Dual Damascene Interconnect Using Low Dielectric Constant Films", S. Giho, August, 2000, pp. 87-92.						
	AS	GIJUTSU JOKO KYOKAI SHUPPAN, 12/27/00, "New Material and Process Technique of the Next Generation of ULSI Interconnect", pp. 295-305.						
	AT							
EXAMINER K. C. [Signature]				DATE CONSIDERED 11-20-03				

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